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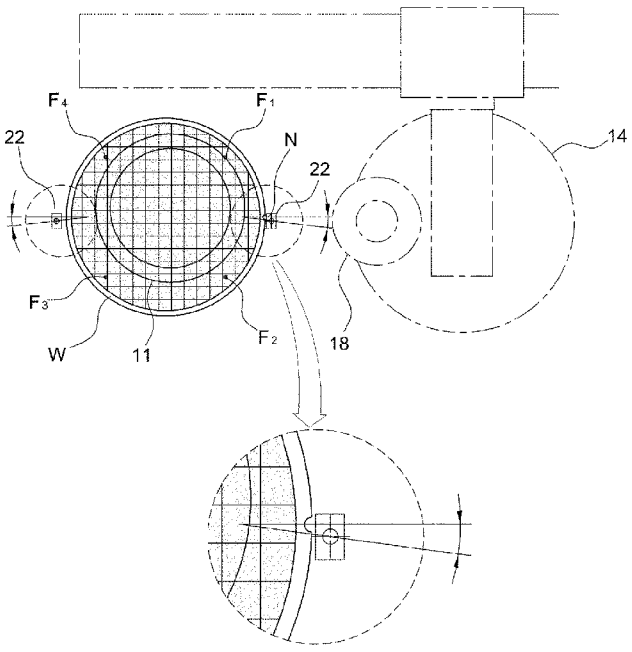
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[다음 쪽 계속]

(54) **Title**: METHOD FOR ALIGNING SEMICONDUCTOR MATERIALS

(54) **발명의 명칭** : 반도체 자재 정렬방법

[Fig. 10]



(57) **Abstract**: The present invention relates to a method which enables the positions of semiconductor materials to be accurately aligned so as to accurately transfer the semiconductor materials to processing positions in an apparatus for manufacturing a semiconductor package. According to the present invention, a wafer-processing apparatus, such as a singulation apparatus or the like that cuts a wafer-type material, in which a plurality of semiconductor packages is arranged into a lattice, into individual semiconductor package units, achieves a novel alignment system in that the alignment relationship between the center of a dowel hole and the center of a semiconductor package is photographed by means of a vision camera, and the positions of the materials in the X-Y-è directions are accurately aligned so as to accurately transfer the materials to the processing positions. Therefore, the wafer-processing apparatus can be actively used in a novel aligning method such as wafer-level packaging or the like. Particularly, the present invention relates to a method for aligning semiconductor materials, which can avoid the influence of errors caused by the vibration of equipment, etc., and ensure accurate measurement values in order to accurately align the materials.

(57) 요약서:

[다음 쪽 계속]

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